

## **Product Change Notification / CENO-12HYAS450**

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19-Dec-2022

## **Product Category:**

Microprocessors

# **PCN Type:**

Manufacturing Change

# **Notification Subject:**

CCB 6009 Initial Notice: Qualification of ASEK as an additional assembly site for selected ATSAMA5D3xx device family available in 324L LFBGA (15x15x1.4mm) package.

### **Affected CPNs:**

CENO-12HYAS450\_Affected\_CPN\_12192022.pdf CENO-12HYAS450\_Affected\_CPN\_12192022.csv

#### **Notification Text:**

**PCN Status:**Initial Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of ASEK as an additional assembly site for selected ATSAMA5D3xx device family available in 324L LFBGA (15x15x1.4mm) package.

## **Pre and Post Change Summary:**

Pre Change	Post Change
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	ATX	ATX Semiconductor	ASE Inc.		
Assembly Site	Semiconductor (Shanghai) Co. Ltd	(Shanghai) Co. Ltd	(ASEK)		
	(ASSH)	(ASSH)			
Wire Material	CuPd	CuPd	CuPdAu		
Die Attach Material	2100AS	2100AS	2100AC		
Molding Compound Material	KE-G1250LKDS	KE-G1250LKDS	KE-G1250NAS		
Substrate Core Material	CCL-HL832NX	CCL-HL832NX	CCL-HL832NX(A-HS)		

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve manufacturability by qualifying ASEK as an additional assembly site

**Change Implementation Status:**In Progress

**Estimated Qualification Completion Date:**April 2023

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

## **Time Table Summary:**

	December 2022				>	April 2023					
Workweek	4 9	5 0	5 1	5 2	5 3		1 3	1 4	1 5	1 6	1 7
Initial PCN Issue Date				Х							
Qual Report Availability											Х
Final PCN Issue Date											Х

Method to Identify Change: Traceability code

**Qualification Plan:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:**December 19, 2022: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

#### Attachments:

PCN\_CENO-12HYAS450\_Qual\_Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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#### Affected Catalog Part Numbers (CPN)

ATSAMA5D35A-CN

ATSAMA5D31A-CU

ATSAMA5D33A-CU

ATSAMA5D34A-CU

ATSAMA5D35A-CU

ATSAMA5D36A-CU

ATSAMA5D31A-CUC21

ATSAMA5D35A-CUC22

ATSAMA5D36A-CUC23

ATSAMA5D36A-CN

ATSAMA5D35A-CNR

ATSAMA5D36A-CNR

ATSAMA5D31A-CUR

ATSAMA5D33A-CUR

ATSAMA5D34A-CUR

ATSAMA5D35A-CUR

ATSAMA5D36A-CUR

ATSAMA5D31A-CURC21

ATSAMA5D35A-CURC22

ATSAMA5D36A-CURC23

Date: Sunday, December 18, 2022